

**Amendments to Specification:**

**Page 4, paragraph 4**

Replace paragraph 4 on page 4 with the following amended paragraph.

It is an object of the invention to provide a cavity down ball grid array package in which the recess has substrate circuitry in the total recess area, and the circuitry allows multiple signal types and voltages under the die.

**Page 5, paragraph 3**

Replace paragraph 3 on page 5 with the following amended paragraph.

In accordance with these and other objectives of the invention, an improved cavity-down ball grid array package is disclosed. It is fabricated from a printed wiring board substrate, which includes an integral heatspreader. Further, the material for the heatspreader may be selected to determine the TCE of the package, and to design the TCE of the package for optimal system reliability. After the printer wiring board is fabricated a recess is formed for an integrated circuit die. The recess is formed without additional material, and without excising a hole in the substrate. Therefore, the recess has substrate circuitry, in the total recess area, for electrical connections to the die, which are made by wirebonds, TAB, or solder balls.